Product Specification

Product Name:

Product Code: TS012832-A04

Customer
Approved by Customer
Approved Date:

CONTENT

REVISION RECORD

REV.	REVISION DESCRIPTION	REV. DATE	REMARK
D01	Initial Release	2015-06-17	

1 Overview

IEO128032M1760 is a monochrome OLED display module with 128×32 dot matrix. The characteristics of this display module are high brightness, self-emission, high contrast ratio, slim/thin outline, wide viewing angle, wide temperature range, and low power consumption.

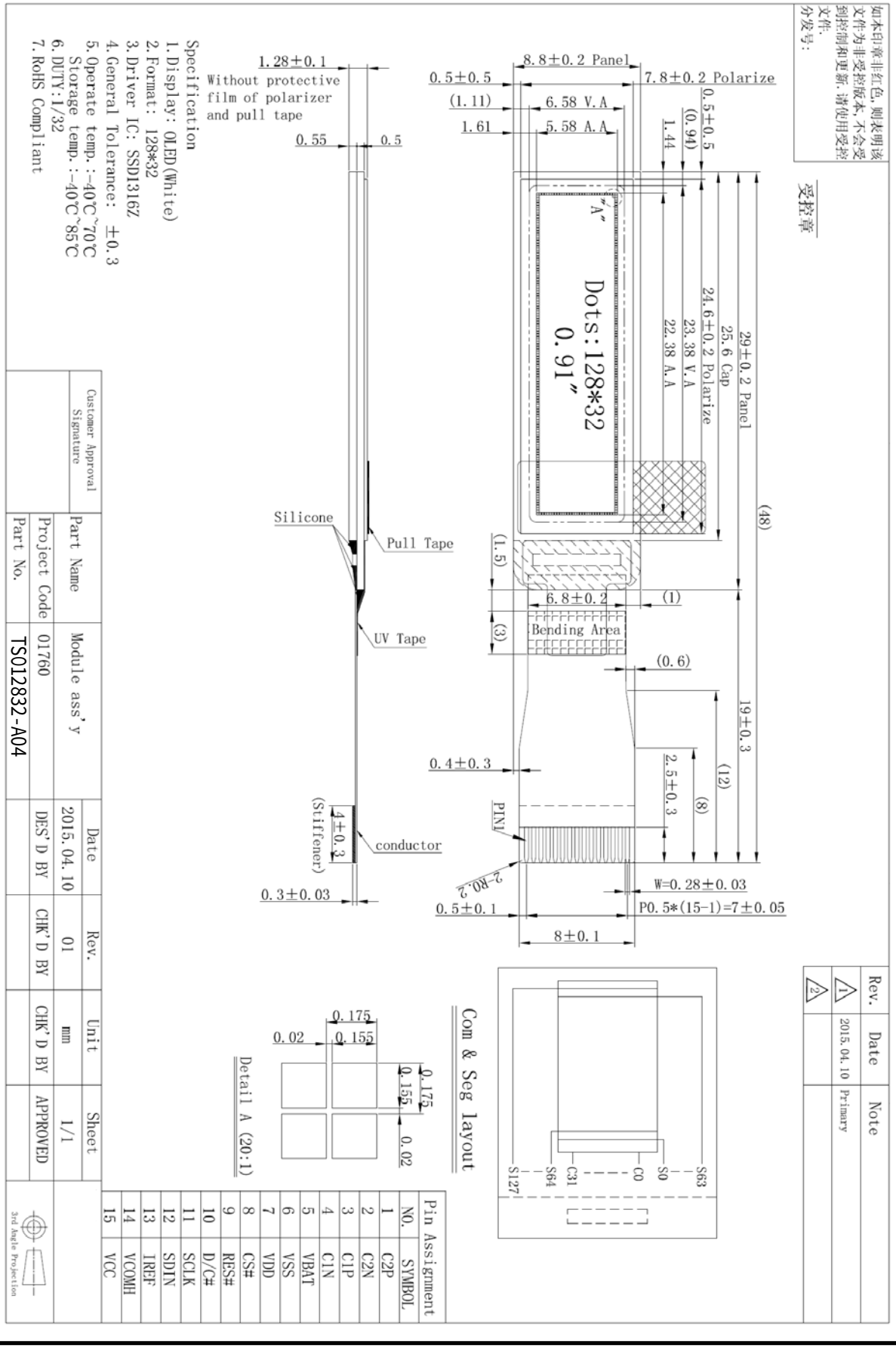
2 Features

- Display Color: White
- Dot Matrix:128×32
- Driver IC: SSD1316Z
- Interface: SPI
- Wide range of operating temperature: -40℃ to 70℃

3 Mechanical Data

NO.	ITEM	SPECIFICATION	UNIT
1	Dot Matrix	128(W)×32(H)	-
2	Dot Size	0.155(W)×0.155(H)	mm^2
3	Dot Pitch	0.175(W)×0.175(H)	mm^2
4	Aperture Rate	78	%
5	Active Area	22.38 (W)×5.58 (H)	mm^2
6	Panel Size	29(W)×8.8(H) ×1.05(T)	mm^3
7	Module Size	48(W)×8.8(H) ×1.28(T)	mm^3
8	Diagonal A/A Size	0.91	inch
9	Module Weight	0.67±10%	gram

4 Mechanical Drawing



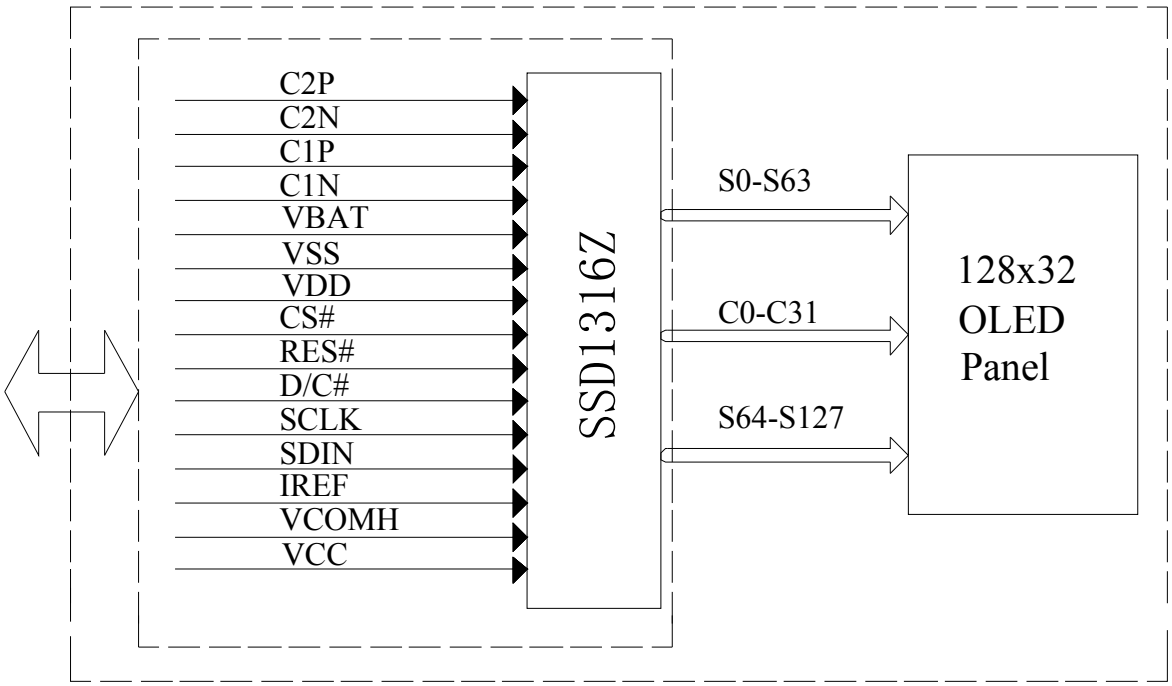
5 Module Interface

PIN NO.	PIN NAME	DESCRIPTION
1	C2P	C1P/C1N – Pin for charge pump capacitor; Connect to each other with a capacitor. C2P/C2N – Pin for charge pump capacitor; Connect to each other with a capacitor.
2	C2N	
3	C1P	
4	C1N	
5	VBAT	Power supply for charge pump regulator circuit. Table 5.1
6	VSS	This is a ground pin.
7	VDD	Power supply pin for core logic operation.
8	CS#	This pin is the chip select input.(active low)
9	RES#	This pin is reset signal input. When the pin is LOW, initialization of the chip is executed.
10	D/C#	The date/command control pin.
11	SCLK	The serial clock pin.
12	SDIN	The serial data pin.
13	IREF	This pin is segment current reference pin. A resistor should be connected between this pin and VSS.
14	VCOMH	This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.
15	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin. When charge pump is enabled, a capacitor should be connected between this pin and VSS.

Table 5.1

Status	VBAT	VDD	VCC
Enable charge pump	Connect to external VBAT source	Connect to external VDD source	A capacitor should be connected between this pin and VSS
Disable charge pump	Keep float	Connect to external VDD source	Connect to external VCC source

6 Function Block Diagram



7 Absolute Maximum Ratings

ITEM	SYMBOL	MIN	MAX	UNIT	REMARK
Supply Voltage	VDD	-0.3	4.0	V	IC maximum rating
	VBAT	-0.3	5.0	V	IC maximum rating
OLED Operating Voltage	VCC	0	16	V	IC maximum rating
Operating Temp.	Top	-40	70	℃	-
Storage Temp	Tstg	-40	85	℃	-

Note (1): All of the voltages are on the basis of "VSS = 0V".

Note (2): Permanent breakage of module may occur if the module is used beyond the maximum rating. The module can be normal operated under the conditions according to Section 8 "Electrical Characteristics". Malfunctioning of the module may occur and the reliability of the module may deteriorate if the module is used beyond the conditions.

8 Electrical Characteristics

8.1 DC Electrical Characteristics

ITEM	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Logic Supply Voltage	VDD	22±3°C, 55±15%R.H	1.65	2.8	3.3	V
Supply Voltage for DC/DC	VBAT	22±3°C, 55±15%R.H	3.0	3.7	4.2	V
OLED Driver Supply Voltage (Generated by Internal DC/DC)	VCC	22±3°C, 55±15%R.H	-	9.0	-	V
High-level Input Voltage	V_{IH}	-	0.8×VDD	-	-	V
Low-level Input Voltage	V_{IL}	-	-	-	0.2×VDD	V
High-level Output Voltage	V_{OH}	-	0.9×VDD	-	-	V
Low-level Output Voltage	V_{OL}	-	-	-	0.1×VDD	V

Note : The VCC input must be kept in a stable value; ripple and noise are not allowed.

8.2 Electro-optical Characteristics

ITEM	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Normal Mode Brightness	L_{br}	All pixels ON(1) (VCC generated by internal DC/DC)	120	150	-	cd/m^2
Normal Mode Power Consumption	Pt	All pixels ON(1) (VCC generated by internal DC/DC)	-	81.4	107.3	mW
ICC,Sleep mode Current	ICC,SLEEP	VDD=1.65V~3.3V VCC=7~15V Display OFF, No panel attached	-	-	20	uA
IDD,Sleep mode Current	IDD,SLEEP	VDD=1.65V~3.3V VCC=7~15V Display OFF, No panel attached	-	-	20	uA
C.I.E(White)	(x)	x,y(CIE1931)	0.26	0.30	0.34	-
	(y)		0.29	0.33	0.37	-
Dark Room Contrast	CR	-	≥2000:1	-	-	-
Response Time	-	-	-	10	-	μs
View Angle	-	-	≥160	-	-	Degree

Note(1): Normal Mode test conditions are as follows:

- Driving voltage: VBAT: 3.7V (VCC Generated by Internal DC/DC).
- Frame rate: 115Hz
- Duty setting: 1/32
- Contrast setting: 0x53

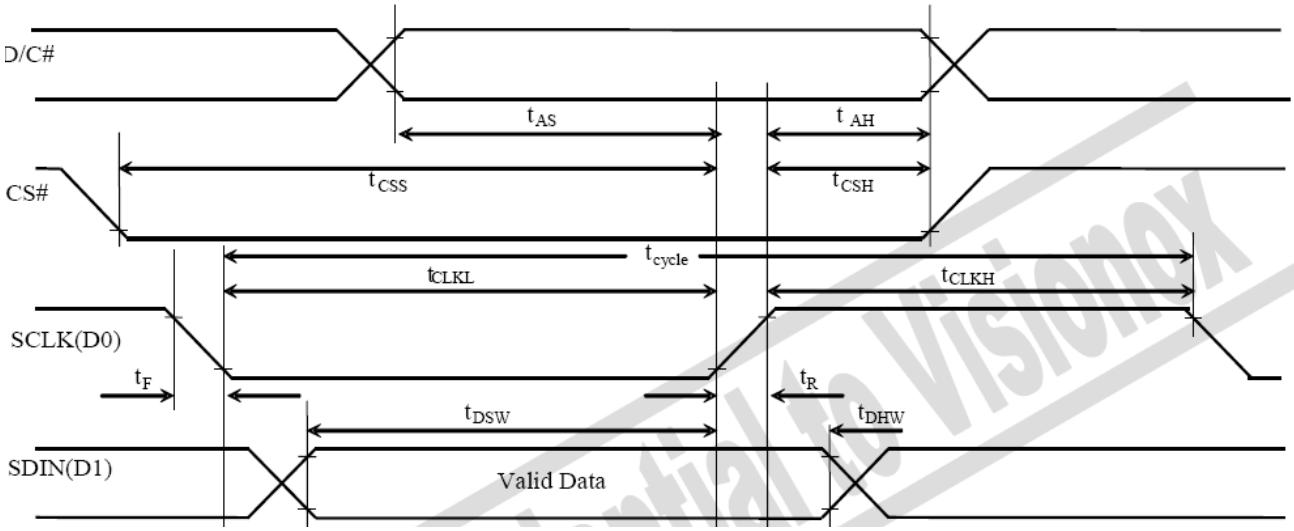
8.3 AC Electrical Characteristics

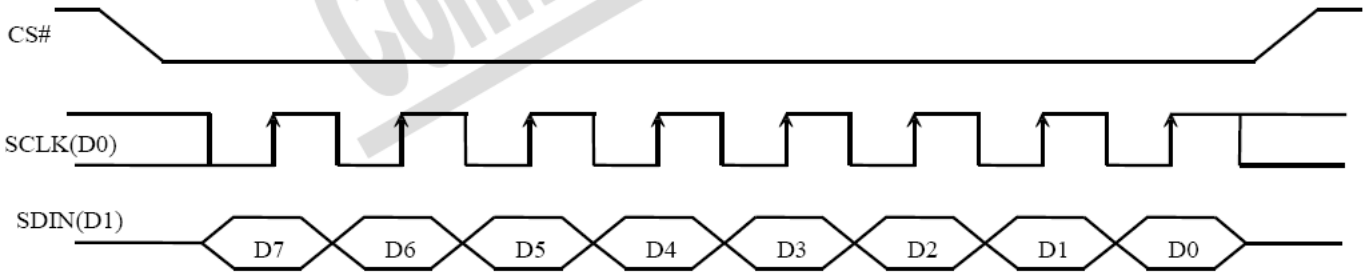
4-wire SPI interface Timing Characteristics

(VDD - VSS = 1.65V to 3.3V, TA = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	100	-	-	ns
t_{AS}	Address Setup Time	15	-	-	ns
t_{AH}	Address Hold Time	15	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	60	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	40	-	-	ns
t_{CLKH}	Clock High Time	60	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns

SPI interface characteristics



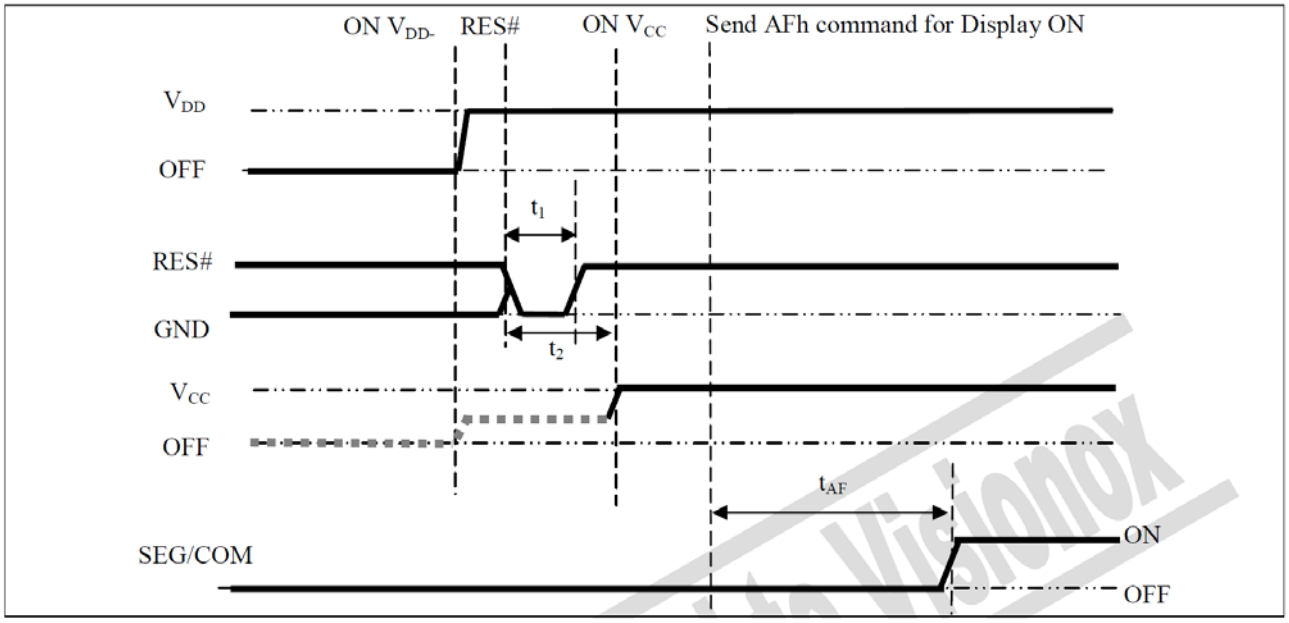


9 Functional Specification and Application Circuit

9.1 Power ON and Power OFF Sequence with External VCC

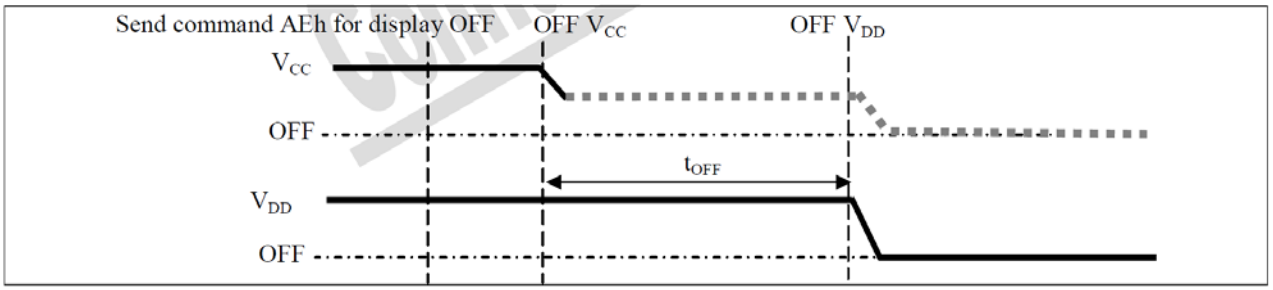
Power ON Sequence:

1. Power ON VDD
2. After VDD become stable, set RES# pin LOW (logic low) for at least 3us (t_1)[4] and then HIGH (logic high).
3. After set RES# pin LOW (logic low), wait for at least 3us (t_2). Then Power ON VCC[1].
4. After VCC become stable, send command AFh for display ON. SEG/COM will be ON after 100ms (t_{AF}).



Power OFF Sequence:

1. Send command AEh for display OFF.
2. Power OFF VCC[1] [2] [3].
3. Power OFF VDD after t_{OFF}. [5] (Typical t_{OFF}=100ms)



Note:

(1)Since an ESD protection circuit is connected between VDD and VCC, VCC becomes lower than VDD whenever VDD is ON and VCC is OFF as shown in the dotted line of VCC in above figures.

(2) VCC should be kept float (disable) when it is OFF.

(3) Power Pins(VDD, VCC) can never be pulled to ground under any circumstance.

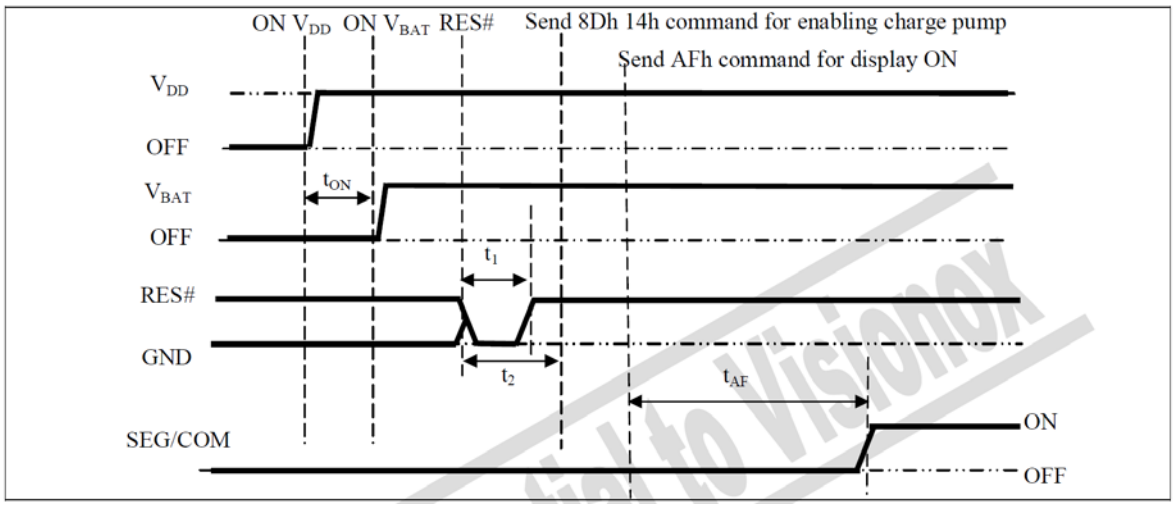
(4) The register values are reset after t1.

(5) VDD should not be Power OFF before VCC Power OFF.

9.2 Power ON and OFF sequence with Charge Pump Application

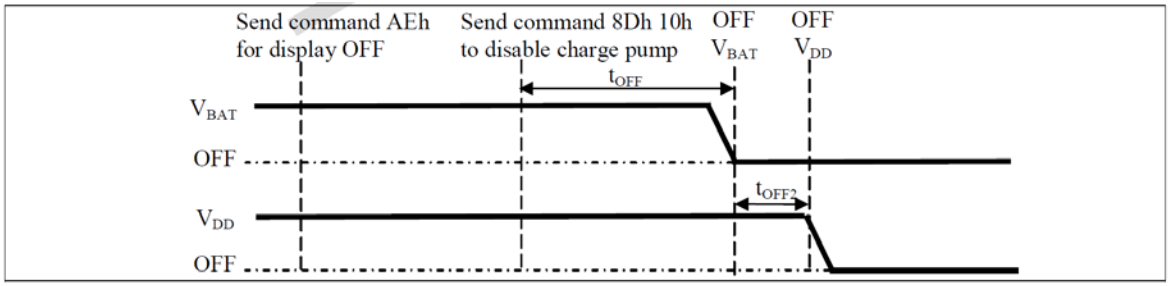
Power ON sequence:

1. Power ON VDD
2. Wait for t_{ON}. Power ON VBAT.[(1), (2)] (where Minimum t_{ON} = 0ms)
3. After VBAT become stable, set RES# pin LOW (logic low) for at least 3us (t1) [(3)] and then HIGH (logic high).
4. After set RES# pin LOW (logic low), wait for at least 3us (t_2). Then input commands with below sequence:
   a. 8Dh 14h for enabling charge pump at 9.0V mode
   b. AFh for display ON
5. SEG/COM will be ON after 100ms (t_{AF}).



Power OFF sequence:

1. Send command AEh for display OFF
2. Send command 8Dh 10h to disable charge pump
3. Power OFF VBAT after t_{OFF}. [(1), (2)] (Typical t_{OFF} =100ms)
4. Power OFF VDD after t_{OFF2}. (where Minimum t_{OFF2} = 0ms [(4)] , Typical t_{OFF2}=5ms)



Note:

(1)VBAT should be kept float (i.e. disable) when it is OFF.

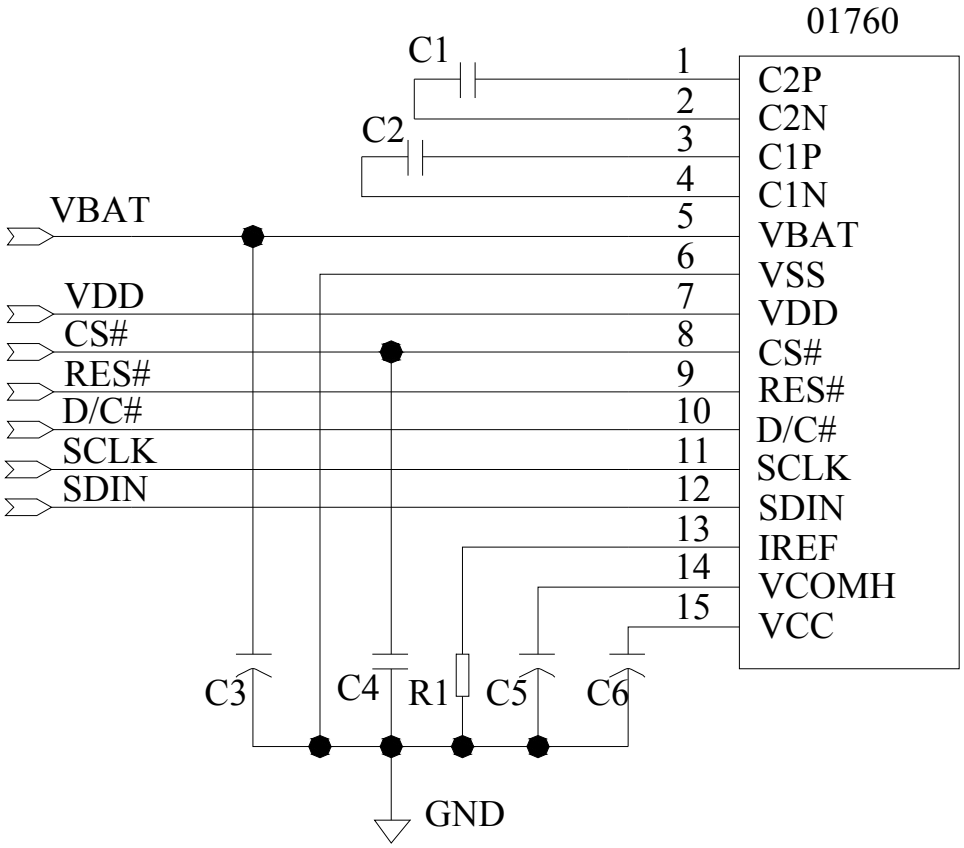
(2) Power Pins (VDD , VBAT) can never be pulled to ground under any circumstance.

(3) The register values are reset after t1.

(4) VDD should not be Power OFF before VBAT Power OFF

9.3 Application Circuit

1) Application Example of M01760 with Internal Charge Pump and SPI mode.



Pin connected to MCU interface: CS#, RES#, D/C#, SCLK, SDIN

Under Internal DC/DC Mode, the Charge Pump Setting (8Dh) must be set as follow:

8Dh: Charge Pump Setting

14h: Enable Charge Pump at 9.0V mode

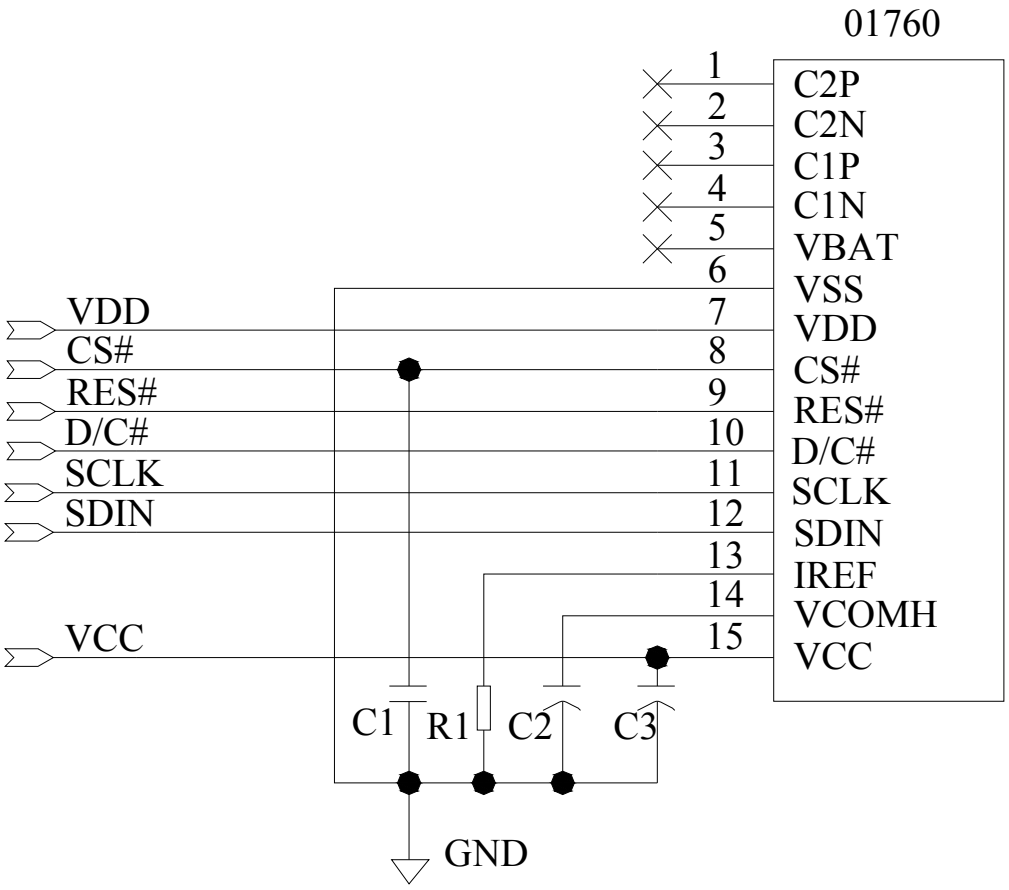
Recommended components

C1, C2, C4: 1uF-0603-X7R±10%.RoHS

C3, C5, C6: 4.7μF/16V.RoHS (Tantalum Capacitors)

R1: 0603 1/10W +/-5% 390Kohm.RoHS

2) Application Example of M01760 with External VCC and SPI mode.



Pin connected to MCU interface: CS#, RES#, D/C#, SCLK, SDIN

C1P, C1N, C2P, C2N, VBAT should be left open.

Under external VCC Mode, the Charge Pump Setting (8Dh) must be set as follow:

8Dh: Charge Pump Setting

10h: Disable Charge Pump

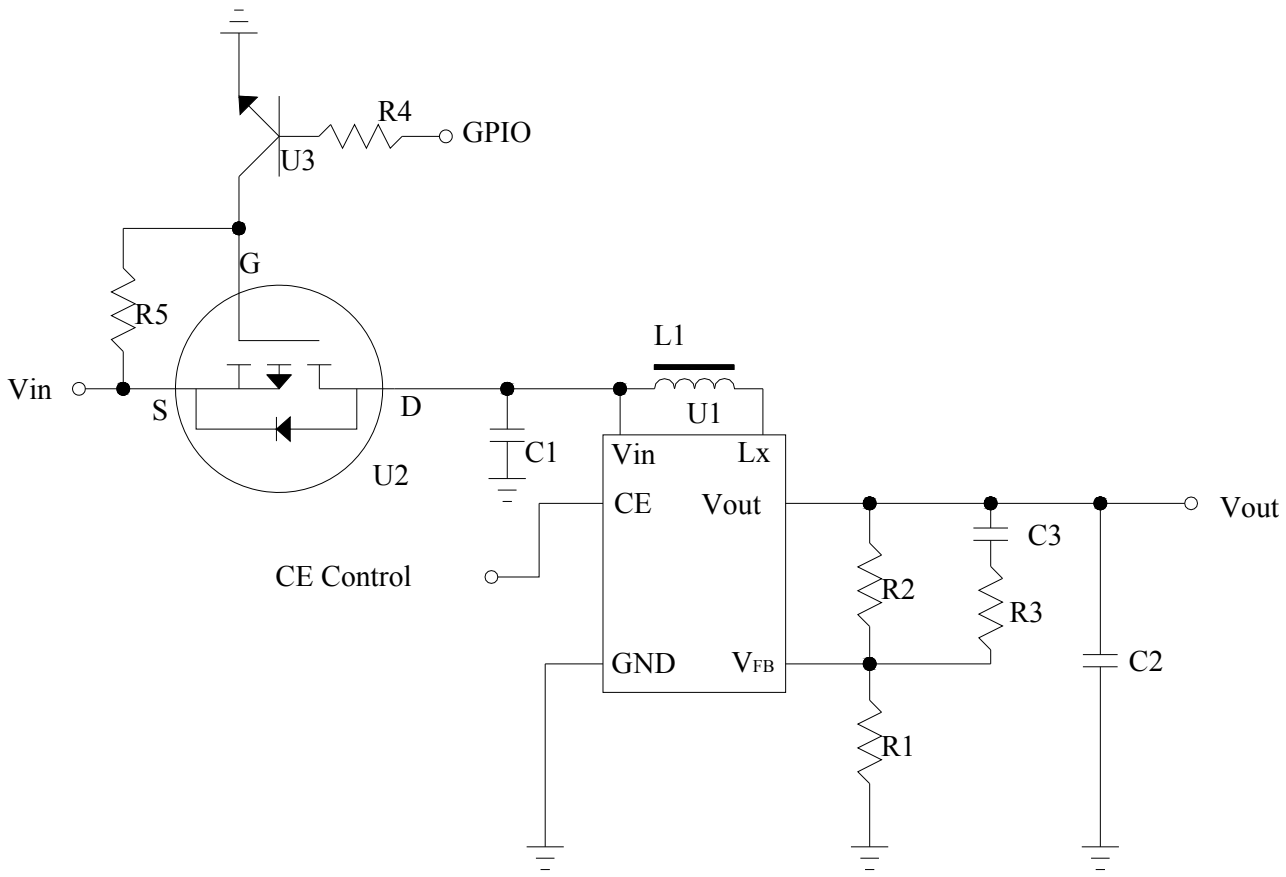
Recommended components

C1: 1uF-0603-X7R±10%.RoHS

C2, C3: 4.7μF/16V.RoHS (Tantalum Capacitors)

R1: 0603 1/10W +/-5% 390Kohm.RoHS

9.4 External DC-DC application circuit



Recommend component

The C1	: 1 uF-0603-X7R±10%.RoHS
The C2	: 1 uF-0603-X7R±10%.RoHS
The C3	: 220pF-0603-X7R±10%.RoHS
The R1	: 0603 1/10W +/-5% 10Kohm.RoHS
The R2	: 0603 1/10W +/-5% 80Kohm.RoHS
The R3	: 0603 1/10W +/-5% 2Kohm.RoHS
The R4	: 0603 1/10W +/-5% 1Kohm.RoHS
The R5	: 0603 1/10W +/-5% 10Kohm.RoHS
The L1	: 22uH
The U1	: R1200
The U2	: FDN338P
The U3	: 8050

9.5 Display Control Instruction

Refer to SSD1316Z IC Specification.

9.6 Recommended Software Initialization

In order to ensure the reliability and stability of the module, the module must initialized use the following code, Malfunctioning of the module may occur and the reliability of the module may deteriorate if the module is used beyond the initialize code.

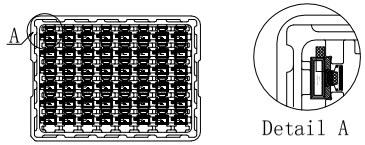
```
void Init_IC()
{
    Write_Command(0xAE);          // Set Display Off
    Write_Command(0xD5);          // Display divide ratio/osc. freq. mode
    Write_Command(0xC1);          // 115HZ
    Write_Command(0xA8);          // Multiplex ration mode:
    Write_Command(0x1F);
    Write_Command(0xAD);          // External or Internal VCOMH/ IREF Selection
    Write_Command(0x00);          // Internal VCOMH/ External IREF
    Write_Command(0x20);          // Set Memory Addressing Mode
    Write_Command(0x02);          // Page Addressing Mode
    Write_Command(0xD3);          // Set Display Offset
    Write_Command(0x00);
    Write_Command(0x40);          // Set Display Start Line
    Write_Command(0x8D);          // DC-DC Control Mode Set
    Write_Command(0x14);          // DC-DC ON/OFF Mode Set
    Write_Command(0xA0);          // Segment Remap
    Write_Command(0xC8);          // Set COM Output Scan Direction
    Write_Command(0xDA);          // Seg pads hardware: alternative
    Write_Command(0x12);
    Write_Command(0x81);          // Contrast control
    Write_Command(0x53);
    Write_Command(0xD9);              // Set pre-charge period
    Write_Command(0x22);
    Write_Command(0xDB);          // VCOMH deselect level mode
    Write_Command(0x00);
    Write_Command(0xA4);          // Set Entire Display On/Off
    Write_Command(0xA6);          // Set Normal Display
    Clear_Screen();
    Write_Command(0xAF);          // Set Display On
}
```

Controlled Seal

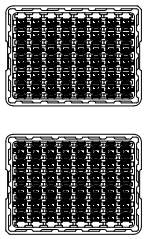
10 Package Specification

Packing Process(1)~(9)

(1) Tray Type:01760-MT6-A

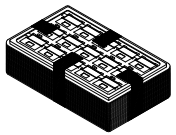


(2)

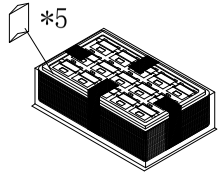


TRAY

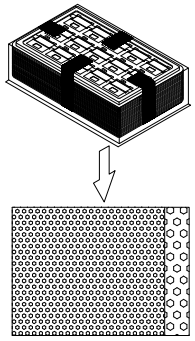
(3) order①、②、①、②
fix trays with tape
1564 pcs of 1 small carton
1 tray contain 68 pcs
23 contained trays, 1 empty tray



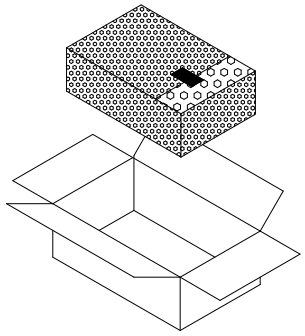
(4) Use vaccum bag to package the tray and add 5 bags of desiccant into the vacuum bag



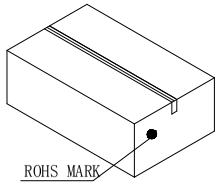
(5) After tray be packaged, wrap the package in a bubble bag and seal with scoth tape.



(6)

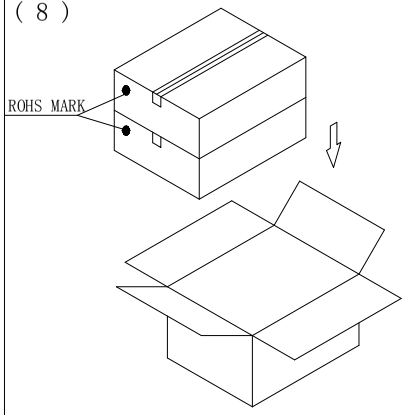


(7)



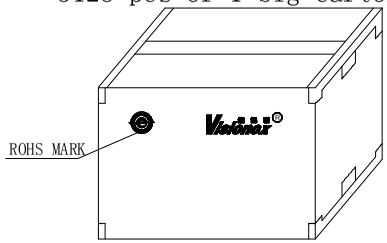
small carton package
L390*W290*L120 mm

(8)



2 small cartons in 1 big carton

(9) 46 contained trays, 2 empty trays,
Package quantity products:
3128 pcs of 1 big carton



Package finished
L410*W310*L272 mm

NOTE:1、The inner carton and master carton must be sealed with adhesive tape.

2、Fill up the gap with tray.

3、If the customer has special needs with the RoHS making, the inner carton and master carton need adhesive new RoHS marking at ⊖.

11 Reliability

11.1 Reliability Test

NO.	ITEM	CONDITION	QUANTITY
1	High Temperature (Non-operation)	85℃,240hrs	4
2	Low Temperature (Non-operation)	-40℃,240hrs	4
3	High Temperature (Operation)	70℃,240hrs	4
4	Low Temperature (Operation)	-40℃,240hrs	4
5	High Temperature / High Humidity (Operation)	60℃,90%RH,240hrs	4
6	Thermal shock (Non-operation)	-40℃~85℃(-40℃/30min;transit/3min;85℃/30min;transit/3min) 1cycle: 66min,30cycles	4
7	ESD (Non-operation)	Air discharge model :+/- 8kV Test nine dots and each dots should be discharged ten times and the interval time can't be less than one second.	4
8	Vibration	Frequency: 5~50Hz,0.5G Scan rate: 1 oct/min Time: 2 hrs/axis Test axis: X,Y, Z	1 Carton
9	Drop	Height: 100 cm Sequence: 1 angle, 3 edges and 6 faces	1 Carton

Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability, the stable time is at least 15 minutes.
2. The degradation of polarizer is ignored for item 5.
3. The tolerance of temperature is ±3℃, and the tolerance of relative humidity is ±5%.

Evaluation criteria

1. The function test is OK.
2. No observable defects.
3. Luminance:≥50% of initial value.
4. Current consumption: within ± 50% of initial value

11.2 Lifetime

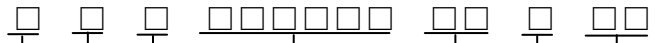
End of lifetime is specified as 50% of initial brightness and the test pattern at operating condition is 50% alternating checkerboard.

ITEM	MIN	MAX	UNIT	CONDITION
Operation Life Time	10,000	-	hrs	150 cd/m^2, 50% alternating checkerboard, 22±3°C, 55±15% RH

11.3 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 22±3°C; 55±15% RH.

12 Illustration of OLED Product Name



Flow No. :

01~99

Display Color :

R—red

G—green

B—blue

Y—yellow

M—amber

W—white

A—area color

F—full color

Panel Flow No. :

A0~A9, B0~B9…Z0~Z9

Display Format :

Graphic—columns and rows

Character—characters and line number

Segment—segment number

Icon—pixel number

Product Type :

P—panel

M—module

Display Type :

G—graphic

C—character

S—segment

I—Icon

M—mixed

Company :

IE—Iexcellence

13 Outgoing Quality Control Specifications

13.1 Sampling Method

(1) GB/T 2828.1/ISO2859-1: Inspection level Ⅱ, normal inspection, single sample inspection

(2) AQL: Major 0.65; Minor 1.0

13.2 Inspection Conditions

The environmental conditions for test and measurement are performed as follows.

Temperature: 22±3°C

Humidity: 55±15%R.H

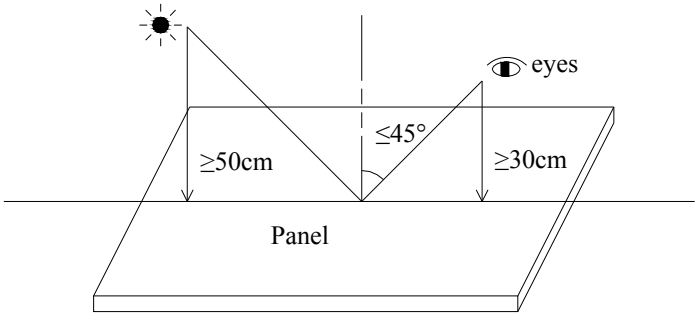
Fluorescent Lamp: 30W

Distance between the Panel & Lamp: ≥50cm

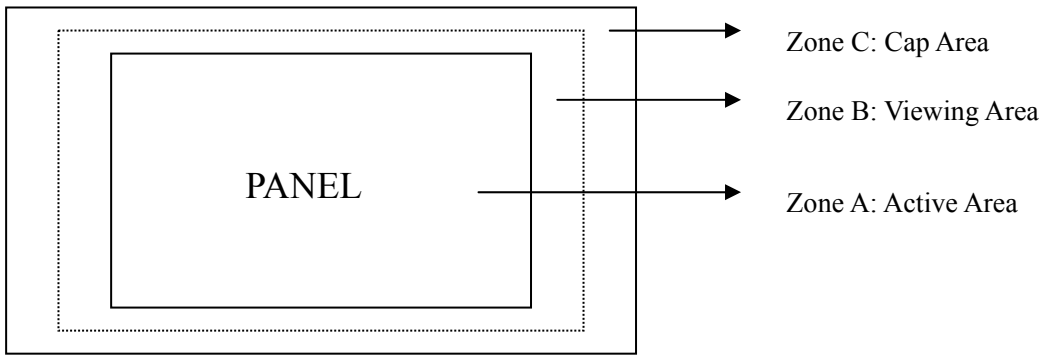
Distance between the Panel & Eyes: ≥30cm

Viewing angle from the vertical in each direction: ≤45°

(See the sketch below)

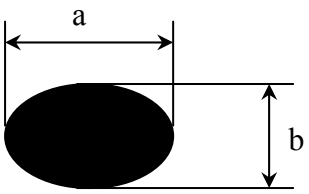


13.3 Quality Assurance Zones

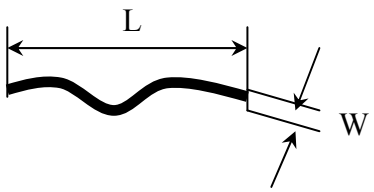


13.4 Inspection Standard

Definition of Φ&L&W (Unit: mm)

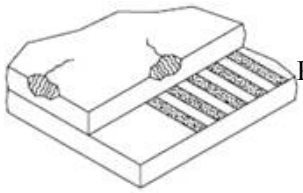
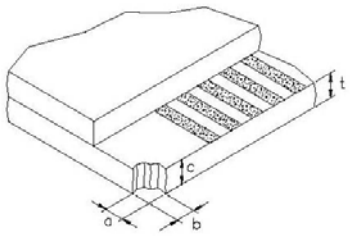
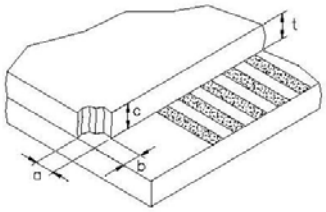
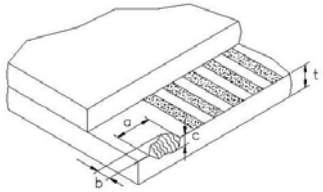
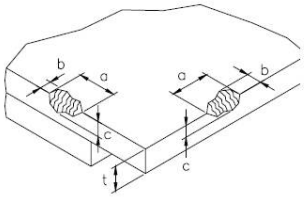
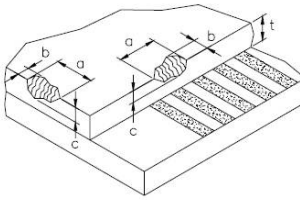


Φ=(a+b)/2



Ⅰ. Appearance Defects

<table>
<tr><th>NO.</th><th>ITEM</th><th>CRITERIA</th><th>CLASSIFICATION</th></tr>
<tr><td>1</td><td>Polarizer Black or White spot, Dirty spot, Foreign matter, Dent on the polarizer</td><td>
<table>
<tr><td rowspan="2">Average Diameter (mm)</td><td colspan="2">Acceptable Number</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>Φ≤0.15</td><td>Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.15<Φ≤0.30</td><td>3</td></tr>
<tr><td>Φ>0.30</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>2</td><td>Scratch/line on the glass/Polarizer</td><td>
<table>
<tr><td rowspan="2">Width (mm)</td><td rowspan="2">Length (mm)</td><td colspan="2">Acceptable Number</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>W≤0.03</td><td>---</td><td>Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.03<W≤0.08</td><td>L≤5.0</td><td>3</td></tr>
<tr><td>W>0.08</td><td>---</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>3</td><td>Polarizer Bubble</td><td>
<table>
<tr><td rowspan="2">Average Diameter (mm)</td><td colspan="2">Acceptable Number</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>Φ>0.5</td><td>0</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.2<Φ≤0.5</td><td>3</td></tr>
<tr><td>Φ≤0.2</td><td>Ignore</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>4</td><td>Any Dirt & Scratch on Polarizer’s Protective Film</td><td>Ignore for not affect the polarizer.</td><td>Minor</td></tr>
<tr><td>5</td><td>Any Dirt on Cap Glass</td><td>
<table>
<tr><td>Average Diameter (mm)</td><td>Acceptable Number</td></tr>
<tr><td>Φ≤0.5</td><td>Ignore</td></tr>
<tr><td>0.5<Φ≤1.0</td><td>3</td></tr>
<tr><td>Φ>1.0</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
</table>

6	Glass Crack	 Propagation crack is not acceptable.	Major
7	Corner Chip	 t= Glass thickness Accept a≤2.0mm or b≤2.0mm, c≤t	Minor
8	Corner Chip on Cap Glass	 t= Glass thickness Accept a≤1.5mm or b≤1.5mm, c≤t	Minor
9	Chip on Contact Pad	 t= Glass thickness Accept a≤3.0mm or b≤0.8mm, c≤t (on the contact pin) a≤3.0mm or b≤1.5mm, c≤t (outside of the contact pin)	Minor
10	Chip on Face of Display	 t= Glass thickness Accept a≤1.5mm or b≤1.5mm, c≤t	Minor
11	Chip on Cap Glass	 t= Glass thickness Accept a≤3.0mm or b≤3.0mm, c≤t/2 a≤1.5mm or b≤1.5mm, t/2≤c≤t	Minor
12	Stain on Surface	Stain removable by soft cloth or air blow is acceptable.	Minor
13	TCP/FPC Damage	(1) Crack, deep scratch, deep hole and deep pressure mark on the TCP/FPC are not acceptable. (2) Terminal lead twisted or broken is not allowable. (3) Copper exposed is not allowed by naked eye inspection.	Minor
14	Dimension Unconformity	Checking by mechanical drawing.	Major

Ⅱ. Displaying Defects

<table>
<tr><th>NO.</th><th>ITEM</th><th>CRITERIA</th><th>CLASSIFICATION</th></tr>
<tr><td>1</td><td>Black/White spot
Dirty spot
Foreign matter</td><td>
<table>
<tr><td rowspan="2">Average Diameter
(mm)</td><td colspan="2">Pieces Permitted</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>Φ≤0.10</td><td>Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.10<Φ≤0.20</td><td>3</td></tr>
<tr><td>Φ>0.20</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>2</td><td>No Display</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>3</td><td>Irregular Display</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>4</td><td>Missing Line
(row or column)</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>5</td><td>Short</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>6</td><td>Flicker</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>7</td><td>Abnormal Color</td><td>Refer to the SPEC.</td><td>Major</td></tr>
<tr><td>8</td><td>Luminance NG</td><td>Refer to the SPEC.</td><td>Major</td></tr>
<tr><td>9</td><td>Over Current</td><td>Refer to the SPEC.</td><td>Major</td></tr>
</table>

14 Precautions for operation and Storage

14.1 Precautions for Operation

(1) Since OLED panel is made of glass, do not apply any mechanical shock or impact or excessive force to it when installing the OLED module. Any strong mechanical impact due to falling dropping etc. may cause damage (breakage or cracking).

(2) The polarizer on the OLED surface is made of soft material and is easily scratched. Please take most care when handing. When the surface of the polarizer of OLED Module is contaminated, please wipe it off gently by using moisten soft cloth with isopropyl alcohol, do not use water, ketone or aromatics. If there is saliva or water on the OLED surface, please wipe it off immediately.

(3) When handling OLED module, please be sure that the body and the tools are properly grounded. And do not touch I/O pins with bare hands or contaminate I/O pins, it will cause disconnection or defective insulation of terminals.

(4) Do not attempt to disassemble or process the OLED module.

(5) OLED module should be used under recommended operating conditions shown in the specification. Since the higher voltage leads to the shorter lifetime, be sure to use the specified operating voltage.

(6) Foggy dew, moisture condensation or water droplets deposited on surface and contact terminals will cause polarizer stain or damage, the deteriorated display quality and electrochemical reaction then leads to shorter life time and permanent damage to the module probably. Please pay attention to the environmental temperature and humidity.

(7) An afterimage is created by the difference in brightness between unused dot and the fixed dot, according to the decrease of brightness of the emitting time. Therefore, to avoid having an afterimage, the full set should be thoroughly used instead of using a fixed dot. When the fixed dot emits, an afterimage can be created.

(8) Flicker could be come out at full on display. And it disappears when frame frequency increase, but brightness decreases too.

14.2 Soldering

(1) Soldering should be performed only on the I/O terminals.

(2) Use soldering irons with proper grounding and no leakage.

(3) Iron:The temperature setting of electric iron is 350℃, but we suggest that during soldering, the tem perature of iron tip should be no higher than 330℃ and soldering be finished within 3~4 seconds.

14.3 Precautions for Storage

(1) Please store OLED module in a dark place. Avoid exposure to sunlight, the light of fluorescent lamp or any ultraviolet ray.

(2) Keep the environment temperature between 10℃ and 35℃ and the relative humidity less than 60%. Avoid high temperature and high humidity.

(3) Keep the OLED modules stored in the container when shipped from supplier before using them is recommended.

(4) Do not leave any article on the OLED module surface for an extended period of time.